

### **Excellent Integrated System Limited**

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Kingbright WP513HDT

For any questions, you can email us directly: <u>sales@integrated-circuit.com</u>



#### 2.5x5mm RECTANGULAR SOLID LAMP

The Bright Red source color devices are made with Gallium

Part Number: WP513HDT

Phosphide Red Light Emitting Diode.

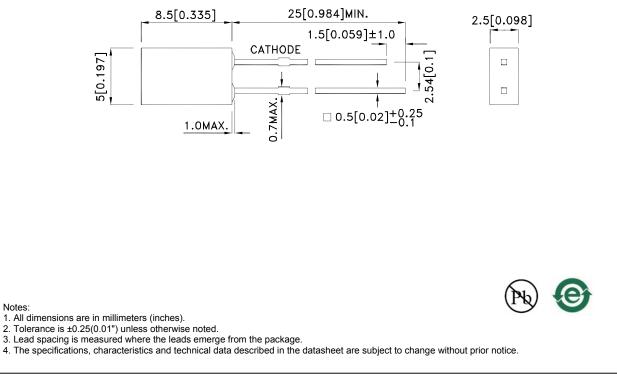
Description

Bright Red

#### Features

- Low power consumption.
- Reliable and rugged.
- Excellent uniformity of light output.
- Suitable for level indicator.
- Long life solid state reliability.
- RoHS compliant.

**Package Dimensions** 



SPEC NO: DSAF2586



#### Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
WP513HDT	Bright Red (GaP)	Red Diffused	0.2	0.6	110°

Notes:

1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Bright Red	700		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Bright Red	635		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Bright Red	45		nm	I⊧=20mA
С	Capacitance	Bright Red	40		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Bright Red	2.25	2.5	V	I⊧=20mA
IR	Reverse Current	Bright Red		10	uA	VR = 5V

Notes:

1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V. 3.Wavelength value is traceable to the CIE127-2007 compliant national standards.

#### Absolute Maximum Ratings at TA=25°C

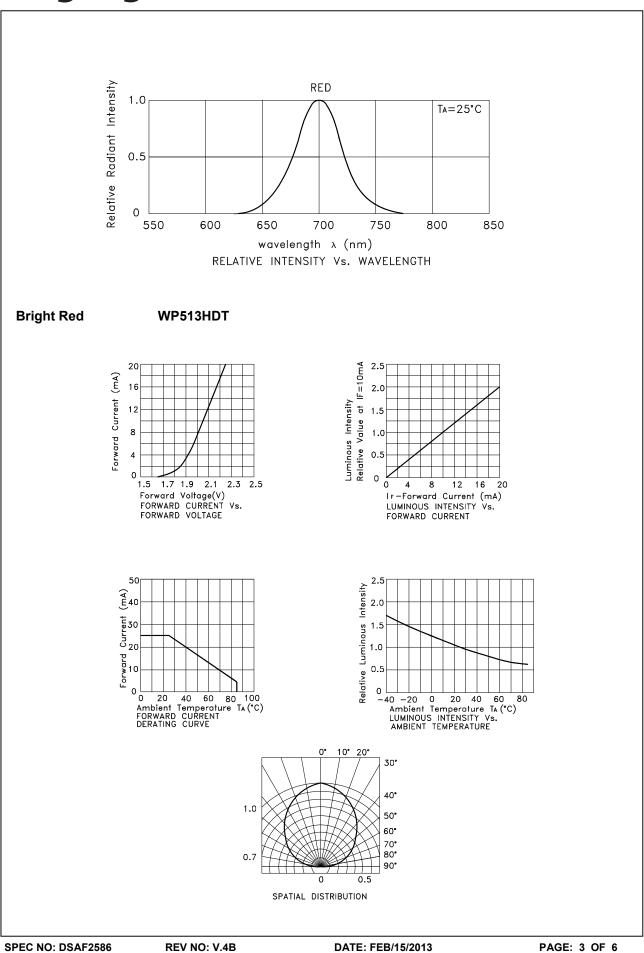
Parameter	Bright Red			
Power dissipation	62.5	mW		
DC Forward Current	25	mA		
Peak Forward Current [1]	130	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C	·		
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds			

1/10 Duty Cycle, 0.1ms Pulse Width.

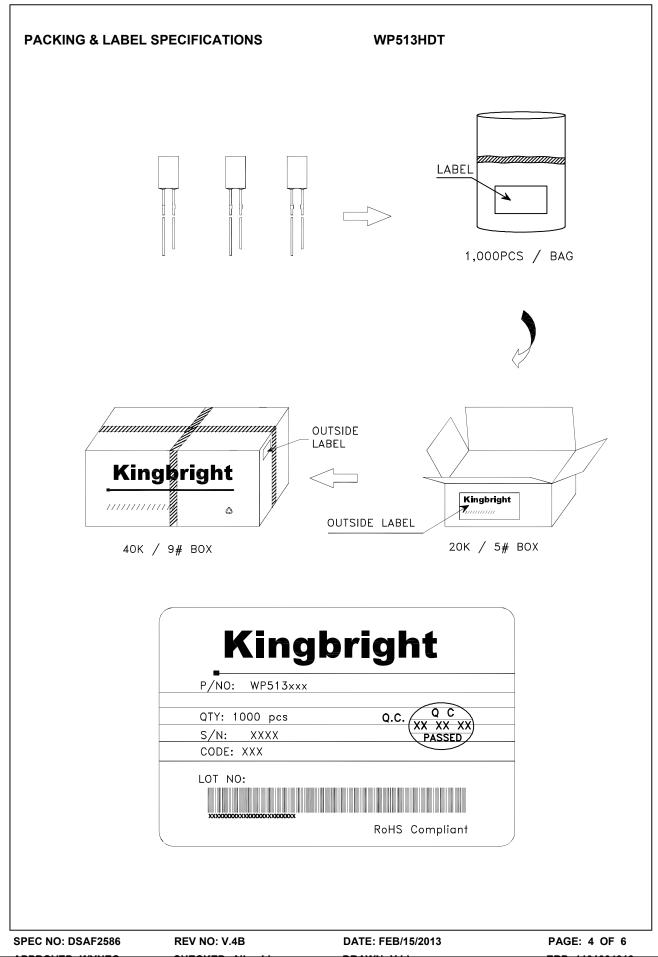
2. 2mm below package base.

3. 5mm below package base.





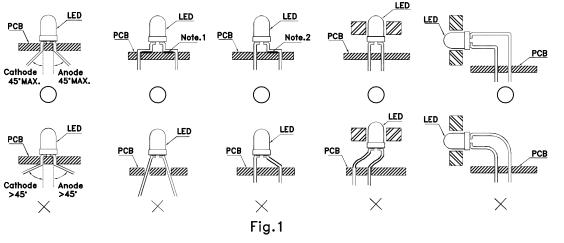






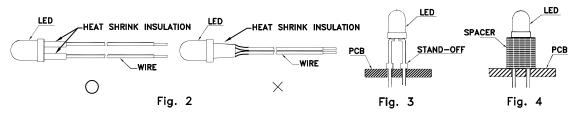
#### PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)



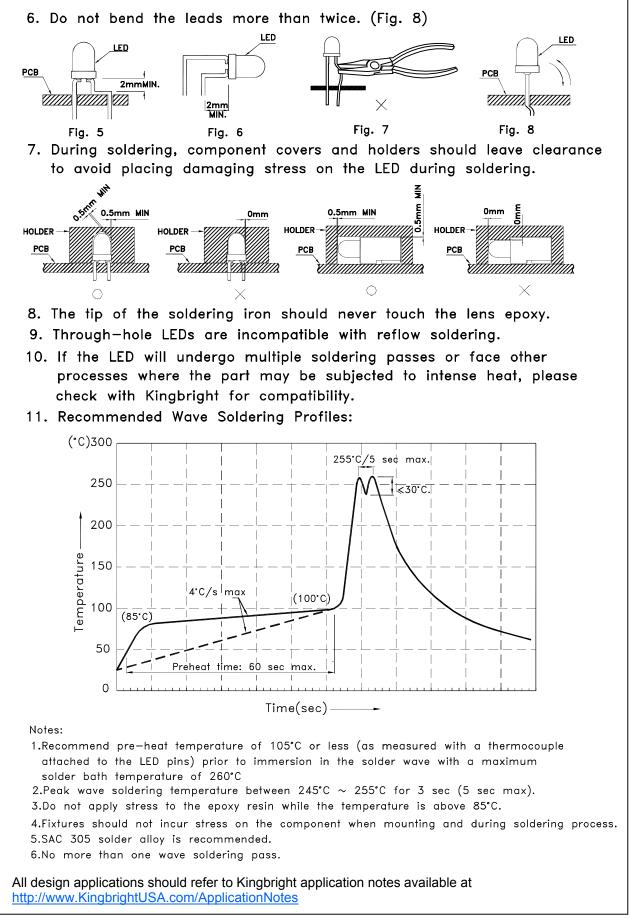
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- d "imes" Incorrect mounting method
- 2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)
- 3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)





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